



Material Content Data Sheet



Sales Product Name				IPD65R600C6		Issued		23. September 2015	
MA#				MA001040760					
Package				PG-TO252-3-341		Weight*		382.83 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.294	0.86	0.86	8604	8604	
leadframe	non noble metal	iron	7439-89-6	0.229	0.06		599		
	inorganic material	phosphorus	7723-14-0	0.069	0.02		180		
	non noble metal	copper	7440-50-8	228.946	59.80	59.88	598033	598812	
wire	non noble metal	aluminium	7429-90-5	4.580	1.20	1.20	11963	11963	
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.669	0.44		4361		
	plastics	brominated resin	-	1.789	0.47		4672		
	organic material	carbon black	1333-86-4	1.908	0.50		4984		
	plastics	epoxy resin	-	16.097	4.20		42048		
	inorganic material	silicondioxide	60676-86-0	97.777	25.54	31.15	255404	311469	
leadfinish	non noble metal	tin	7440-31-5	3.787	0.99	0.99	9892	9892	
plating	non noble metal	nickel	7440-02-0	0.515	0.13	0.13	1346	1346	
solder	noble metal	silver	7440-22-4	0.074	0.02		194		
	non noble metal	tin	7440-31-5	0.059	0.02		155		
	non noble metal	lead	7439-92-1	2.835	0.74	0.78	7406	7755	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.00		50		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15		
	non noble metal	copper	7440-50-8	19.177	5.01	5.01	50094	50159	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com